

RECEIVED
CENTRAL FAX CENTER
JUN 22 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yoshino Docket No: TI-29448
Serial No: 09/909,013 Examiner: Geyer, Scott
Filed: 7/19/2001 Art Unit: 2829
For: SEMICONDUCTOR PACKAGE INSULATION FILM AND
MANUFACTURING METHOD THEREOF

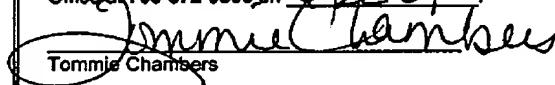
OFFICIAL

EXTENSION OF TIME

Assistant Commissioner For Patents
Washington, DC 20231

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being
transmitted by facsimile to the U.S. Patent and Trademark
Office at 703-872-9306 on 6/22/04:


Tommie Chambers

Dear Sir:

Pursuant to 37 CFR 1.136(a), Applicant(s) respectfully petition(s) the Commissioner for
an extension of the shortened statutory period for response in the above identified Application.

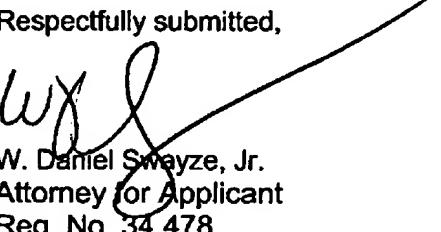
The fee for this extension is indicated below:

One Month (\$110)
 Two Months (\$390)

Three Months (\$890)
 Four Months (\$1,390)

Any further necessary extension of time is hereby requested. Charge any and all fees,
or credit any overpayment, to the deposit account of Texas Instruments Incorporated, Account
No. 20-0668.

Respectfully submitted,


W. Daniel Swayze, Jr.
Attorney for Applicant
Reg. No. 34,478

Texas Instruments Incorporated
P.O. Box 655474, MS 3999
Dallas, TX 75265
(972) 917-5633

To: T chonology Unit: 2829
Facsimile Number: 703-872-9306

Total Pages Sent 12

From: W. Daniel Swayze, Jr.
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-917-5633

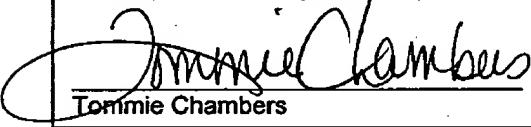
RECEIVED
CENTRAL FAX CENTER
JUN 22 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

OFFICIAL

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on the date shown below:


Tommie Chambers

6-22-04
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT _____ (12 Pages)
<input type="checkbox"/> NEW APPLICATION	<input checked="" type="checkbox"/> EOT _____ (1 Month)
<input type="checkbox"/> DECLARATION (# Pages)	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> ASSIGNMENT (# Pages)	<input type="checkbox"/> APPEAL _____ (# Pages)
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE (# Pages)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> CHANGE IN CORRESPONDENCE
<input type="checkbox"/> CONTINUATION APP'N (# Pages)	<input type="checkbox"/> ADDRESS
<input type="checkbox"/> DIVISIONAL APP'N	
NAME OF INVENTOR(S): Yoshino	
TITLE OF INVENTION: SEMICONDUCTOR PACKAGE INSULATION FILM AND MANUFACTURING METHOD THEREOF	
TI FILE NO.: TI-29448	DEPOSIT ACCT. NO.: 20-0668
FAXED: 6-22-04 DUE: 05/27/04 ATTY/SECY: wds/tc	
RECEIPT DATE & SERIAL NO.: Serial No.: 09/909,013 Filing Date: 7/19/2001	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265